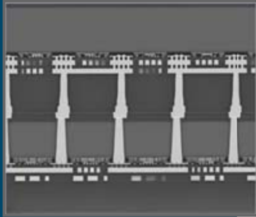
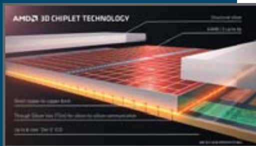
Advanced Packaging Update:

Market and Technology Trends

Vol. 2-0724





This issue of the Advanced Packaging Update features a detailed financial analysis of the top 20 OSATs, chiplet packaging applications and a market forecast, and HBM trends. A special section on RDL as an alternative to silicon interposer is included. Developments in build-up substrates are presented, along with an assessment of alternatives such as glass, silicon, and ceramic core substrates. Substrate design rules are presented for worldwide suppliers of laminate flip chip BGA and CSP substrates. Body size, core thickness, via and pad diameter, minimum bump pitch supported, and substrate finish offerings are included.

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